

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS2290	Sep-96	9632 K	DALLAS	DA084400	PCB	SIPSTIK

STRESS/JOB NO.

READPOINT
(Sample Size/No. of Fails)

Hi Temp Storage 85°C, No Bias P-18163	<u>336 Hr</u> 11/0	<u>1000 Hr</u> 11/0	<u>Cum %</u> 0.0%
Temp Cycle -40°C to +85°C P-18164	<u>100 ~</u> 11/0	<u>500 ~</u> 11/0	<u>Cum %</u> 0.0%
Moisture Soak 60°C / 90% R.H. P-18165	<u>192 Hr</u> 11/0	<u>384 Hr</u> 11/0	<u>Cum %</u> 0.0%

Failure Mode

Failure Analysis